**Japan Silicon Wafer TC Chapter**  
*Meeting Fall and Minutes*  
*Japan Summer Standards Meeting*  
Friday, September 9, 2016, 13:30-17:00  
SEMI Japan Office, Tokyo, Japan

**Next TC Chapter Meeting**  
Thursday, December 15, 2016, 13:00-17:00,  
Meeting Room, Tokyo Big Sight, Tokyo, Japan

**Table 1 Meeting Attendees**  
Co-Chairs: Naoyuki Kawai (University of Tokyo), Tetsuya Nakai (SUMCO)  
SEMI Staff: Junko Collins (SEMI Japan)

<table>
<thead>
<tr>
<th>Company</th>
<th>Last</th>
<th>First</th>
<th>Company</th>
<th>Last</th>
<th>First</th>
</tr>
</thead>
<tbody>
<tr>
<td>University of Tokyo</td>
<td>Kawai</td>
<td>Naoyuki</td>
<td>Global Wafers Japan</td>
<td>Takeda</td>
<td>Ryuji</td>
</tr>
<tr>
<td>Kumai Consulting</td>
<td>Kumai</td>
<td>Sadao</td>
<td>Shin’etsu-Handotai</td>
<td>Toda</td>
<td>Naohisa</td>
</tr>
<tr>
<td>SUMCO</td>
<td>Nakai</td>
<td>Tetsuya</td>
<td>-</td>
<td>Yoshi</td>
<td>Masanori</td>
</tr>
<tr>
<td>Hitachi High Technologies</td>
<td>Ikota</td>
<td>Masami</td>
<td>Otsuka Electronics</td>
<td>Mishim</td>
<td>Shunsuke</td>
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<td></td>
<td></td>
<td></td>
<td>SEMI Japan</td>
<td>Collins</td>
<td>Junko</td>
</tr>
</tbody>
</table>

**Table 2 Leadership Changes**  
No Leadership changes

**Table 3 Ballot Results**  
No Ballot Review  
Passed ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.  
Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.  
No ballot review

**Table 4 Authorized Ballots**  
No authorized ballot
Table 5 Authorized Activities

No authorized activity

<table>
<thead>
<tr>
<th>Document #</th>
<th>Type</th>
<th>SC/TF/WG</th>
<th>Details</th>
</tr>
</thead>
</table>

Note: SNARFs and TFOFs are available for review on the SEMI Web site at: http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 6 New Action Items

<table>
<thead>
<tr>
<th>Item #</th>
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</tr>
</thead>
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<tr>
<td>SiW160909-01</td>
<td>Ryuji Takeda, Tetsuya Nakai</td>
<td>Background: GCS members held a meeting and suggested plan to remove terms out of M59, Terminology for Silicon Technology, and place them back to the original standards when they are due for 5 year Review</td>
</tr>
<tr>
<td></td>
<td></td>
<td>For effective discussion, Japan Chapter will propose a counter suggestion.</td>
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<td></td>
<td>Ryuji Takeda to create a counter proposal</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Tetsuya Nakai to bring it up at the appropriate meeting during SEMICON Europa in October.</td>
</tr>
</tbody>
</table>

Action Items from Previous meetings
1 Welcome, Reminders, and Introductions
Naoyuki Kawai, committee co-chair, called the meeting to order at 13:30. Self-introductions were made followed by the agenda review.

2 Required Meeting Elements
The meeting reminders on program membership requirement, antitrust issues, intellectual property issues and international effective meeting guidelines, were reviewed by Junko Collins.

Attachment: Required_Elements_Reg_20150327_E+J_2016StdTemplate

3 Review of Previous Meeting Minutes
The committee reviewed the minutes of the previous meeting held on June 10, 2016.

Motion: To approve the minutes of the previous meeting.
By / 2nd: Tetsuya Nakai (SUMCO) / R. Takeda (Global Wafers Japan)
Discussion: None
Vote: 7 in favor and 0 opposed. Motion passed.

Attachment:

4 SEMI Staff Report
Junko Collins gave the SEMI staff report. This report included Global SEMI Events, Global Standards Meetings Schedule, Ballot Critical Dates, Publication Update, A&R Ballot Review and Contact Information.

Of not, the meeting schedule during SEMICON Japan was reviewed and all participants agreed upon the attached schedule.

Attachment: SEMI Staff Report 20160908_v1.0
2016_STD 会議棟割当_20160909a
5 Liaison Reports

5.1 Japan Regional Standards Committee (JRSC)
Some high lights were included in the staff report and no other special report from the last JRSC meeting.
Attachment: None

5.2 Global Coordinating Subcommittee (GCS)
Tetsuya Nakai reported for the Global Coordinating Subcommittee (GCS). Of note;
• GCS members held a meeting and suggested plan to remove terms out of M59, Terminology for Silicon Technology, and place them back to the original standards when they are due for 5 year review
✓ Ryji Takeda will draft a counter proposal and Tetsuya Nakai will bring it up for more discussion during SEMICON Europa.
Attachment: None

5.3 North America Silicon Wafer TC Chapter
North America Silicon Wafer TC Chapter liaison report was presented by T. Nakai. 
Please see details in the attachments.
Attachment: NA Silicon Wafer TC Liaison Report August 2016

5.4 Europe Silicon Wafer Committee
Europe Silicon Wafer TC Chapter did not have any meeting since last fall. Hence, no report was submitted.
Attachment: None

5.5 JSNM Report
Nao Kawai reported.
• Masayoshi Yoshise has been accepted as SEMI liaison member for M4S (Material Standards Study Group for Semiconductor Supply-Chain). He will participate as observer at the meeting from now on.
• Several round-robins started in M4S
Attachment: None
6 Ballot Review

No ballot review at this meeting.

Attachment: none

7 Task Force Reports

7.1 International 450mm Shipping Box Task Force / JA Shipping Box Task Force

The task force reviewed the following documents and decided to put these documents into “inactive” status.

M26-0304 (Reapproved 1110): Guide for the Re-Use of 100, 125, 150, and 200 mm Wafer Shipping Boxes Used to Transport Wafers

M29-1296 (Reapproved 1110): Specification for 300 mm Shipping Box

The following motion and second procedure has been taken at this TC Chapter meeting for confirmation.

Motion: To approve to change document status of M26 and M29 to “inactive”.

By / 2nd: Tetsuya Nakai (SUMCO) / S. Kumai (Kumai Consulting)

Discussion: None

Vote: 7 in favor and 0 opposed. Motion passed.

Attachment: 450mm SB-TF_Report_160907

7.2 International Advanced Wafer Geometry Task Force / Japan AWG Task Force

Masanori Yoshise reported for the International Advanced Wafer Geometry Task Force / the Japan AWG Task Force. Please see the attachment for details.

Attachment: AWG from SEMI West 2016

7.3 International Polished Wafer Task Force / International 450mm Wafer Task Force

There was no special report.

Attachment: None

7.4 International Epitaxial Wafers Task Force

There was no particular report.

Attachment: None

7.5 International Annealed Wafers Task Force

There no particular report.

Attachment: None

7.6 International Terminology Task Force

See GCS Report.

Attachment: None
7.7 *International SOI Wafers Task Force*

There was no meeting and no particular report.

**Attachment:** Non

7.8 *International Test Method Task Force / Japan Test Method Task Force*

Ryuji Takeda reported for the International Test Method Task Force. Of note;

- The TF is working on 5737B for submitting to the earlier ballot cycle in 2017.
- See other details in the attachment.

**Attachment:** Meeting Minutes of Japan Test Method TF on Jun 9th 2016_v0

7.9 *International Advanced Surface Inspection Task Force*

Masami Ikota reported for the International Advanced Surface Inspection Task Force. Of note,

- Doc. 5995 was submitted to Cycle 6. Return rate does not reach to 60% as of today. So far no reject.
- At the task force during SEMICON West 2016, Intel gave a technical presentation and stated users expected the test method for wafer management using actual defect. This will be discussed among the task force. Any feedback is welcomed from wafer makers in Japan.

**Attachment:** None

7.10 *Fiducial Mark Interoperability Task Force*

Tetsuya Nakai reported for the Fiducial Mark Interoperability Task Force.

- No special report.

**Attachment:** None

7.11 *TC Chapter Project*

The following items are reviewed at the meeting.

- **3-year Project Period**
  
  No documents to be expanded the project period.

- **Consideration of 5-year review**
  
  Currently no document has to be considered.

**Attachment:**

- Silicon Project Period Review 2016.09.09a

  5 years for Si Wafer September 2016
8 Old Business

8.1 Previous Meeting Action Items

Junko Collins reviewed the previous meeting action items.

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<tr>
<td>SiW160610-01</td>
<td>Junko Collins</td>
<td>To push gain Shipping Box Task Force leaders SEMI M26-0304 (Reapproved 1110) and SEMI M29-1296 (Reapproved 1110) to be the documents for five year review. done</td>
</tr>
</tbody>
</table>

9 New Business

No new business.

After some discussion on marking on wafers defined in M12 and M13 which are currently under ballot as Doc. 6061 and doc. 6062 (both Cycle 7), it was decided no further action will be taken by the TC chapter.

6061: Reapproval of SEMI M12-0706 (Reapproved 1011): Specification for Serial Alphanumeric Marking of the Front Surface of Wafers

6062: Reapproval of SEMI M13-0706 (Reapproved 1011), Specification for Alphanumeric Marking of Silicon Wafers

10 Action Item Review

10.1 New Action Items

Junko Collins reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

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Ryuji Takeda to create a counter proposal  
Tetsuya Nakai to bring it up at the appropriate meeting during SEMICON Europa in October. |

11 Next Meeting and Adjournment

The next meeting of the Japan Chapter of Global Silicon Wafer Technical Committee is scheduled for Thursday, December 15 2016, 13:00-17:00, Tokyo Big Sight, Tokyo Japan

Having no further business, a motion was made to adjourn the Japan Chapter of Global Silicon Wafer Technical Committee meeting on September 9 in conjunction with the Japan Standards Fall Meeting.

Adjournment was at 16:40.
Minutes respectfully submitted by:
Junko Collins
Director, Standards & EHS
SEMI Japan
jcollins@semi.org

Minutes approved by:

<table>
<thead>
<tr>
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<th>Position</th>
</tr>
</thead>
<tbody>
<tr>
<td>Naoyuki Kawai</td>
<td>(The University of Tokyo), Co-chair</td>
</tr>
<tr>
<td>Tetsuya Nakai</td>
<td>(SUMCO), Co-chair</td>
</tr>
</tbody>
</table>

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Junko Collins at the contact information above.